

# 74HC138; 74HCT138

3-to-8 line decoder/demultiplexer; inverting

Rev. 5 — 26 January 2015

Product data sheet

## 1. General description

The 74HC138; 74HCT138 decodes three binary weighted address inputs (A0, A1 and A2) to eight mutually exclusive outputs (Y0 to Y7). The device features three enable inputs ( $\bar{E}1$ ,  $\bar{E}2$  and E3). Every output will be HIGH unless  $\bar{E}1$  and  $\bar{E}2$  are LOW and E3 is HIGH. This multiple enable function allows easy parallel expansion to a 1-of-32 (5 to 32 lines) decoder with just four '138' ICs and one inverter. The '138' can be used as an eight output demultiplexer by using one of the active LOW enable inputs as the data input and the remaining enable inputs as strobes. Inputs include clamp diodes. This enables the use of current limiting resistors to interface inputs to voltages in excess of  $V_{CC}$ .

## 2. Features and benefits

- Complies with JEDEC standard no. 7A
- Input levels:
  - ◆ For 74HC138: CMOS level
  - ◆ For 74HCT138: TTL level
- Demultiplexing capability
- Multiple input enable for easy expansion
- Ideal for memory chip select decoding
- Active LOW mutually exclusive outputs
- ESD protection:
  - ◆ HBM JESD22-A114F exceeds 2000 V
  - ◆ MM JESD22-A115-A exceeds 200 V
- Multiple package options
- Specified from  $-40^{\circ}\text{C}$  to  $+85^{\circ}\text{C}$  and from  $-40^{\circ}\text{C}$  to  $+125^{\circ}\text{C}$

## 3. Ordering information

Table 1. Ordering information

Type number	Package			
	Temperature range	Name	Description	
74HC138N	$-40^{\circ}\text{C}$ to $+125^{\circ}\text{C}$	DIP16	plastic dual in-line package; 16 leads (300 mil)	SOT38-4
74HCT138N				
74HC138D	$-40^{\circ}\text{C}$ to $+125^{\circ}\text{C}$	SO16	plastic small outline package; 16 leads; body width 3.9 mm	SOT109-1
74 HCT138D				
74HC138DB	$-40^{\circ}\text{C}$ to $+125^{\circ}\text{C}$	SSOP16	plastic shrink small outline package; 16 leads; body width 5.3 mm	SOT338-1
74HCT138DB				



Table 1. Ordering information ...continued

Type number	Package				
	Temperature range	Name	Description		Version
74HC138PW	-40 °C to +125 °C	TSSOP16	plastic thin shrink small outline package; 16 leads; body width 4.4 mm		SOT403-1
74HCT138PW					
74HC138BQ	-40 °C to +125 °C	DHVQFN16	plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads; 16 terminals; body 2.5 × 3.5 × 0.85 mm		SOT763-1
74HCT138BQ					

## 4. Functional diagram

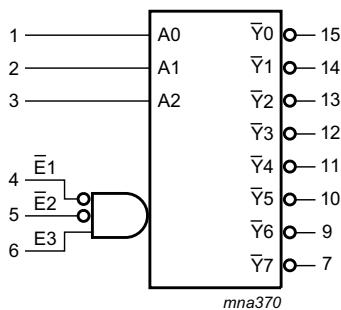


Fig 1. Logic symbol

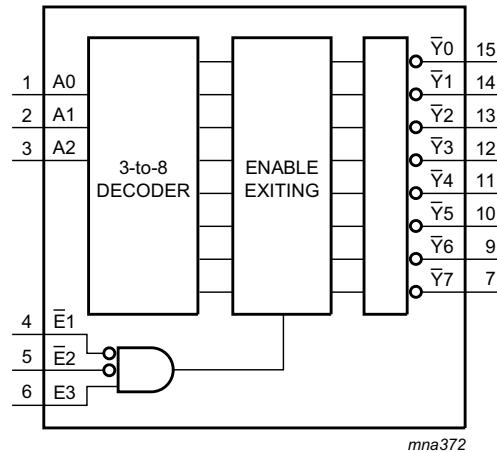


Fig 2. Functional diagram

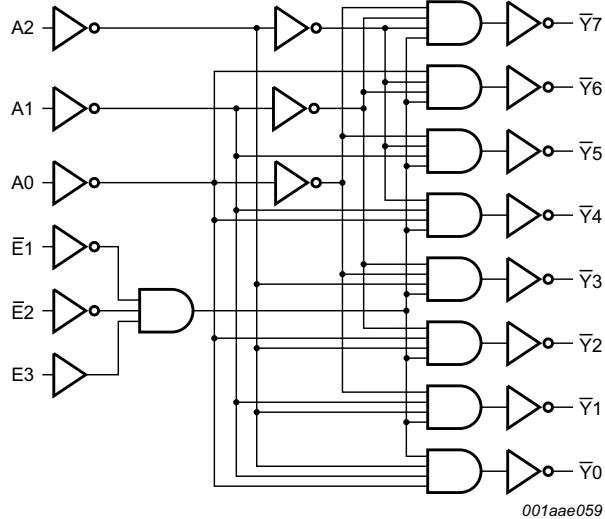


Fig 3. Logic diagram

## 5. Pinning information

### 5.1 Pinning

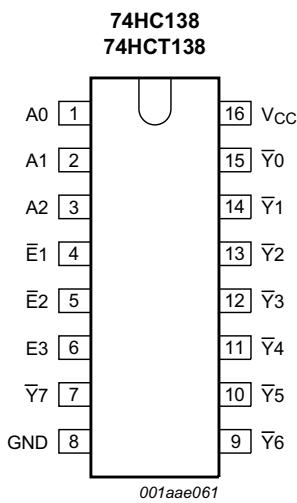
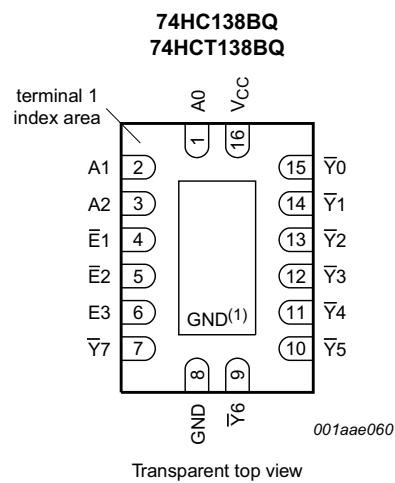


Fig 4. Pin configuration DIP16, SO16, SSOP16 and TSSOP16



- (1) This is not a supply pin. The substrate is attached to this pad using conductive die attach material. There is no electrical or mechanical requirement to solder this pad. However, if it is soldered, the solder land should remain floating or be connected to GND.

Fig 5. Pin configuration DHVQFN16

### 5.2 Pin description

Table 2. Pin description

Symbol	Pin	Description
A0, A1, A2	1, 2, 3	address input A0, A1, A2
$\bar{E}1$ , $\bar{E}2$	4, 5	enable input $\bar{E}1$ , $\bar{E}2$ (active LOW)
E3	6	enable input E3 (active HIGH)
$\bar{Y}0$ , $\bar{Y}1$ , $\bar{Y}2$ , $\bar{Y}3$ , $\bar{Y}4$ , $\bar{Y}5$ , $\bar{Y}6$ , $\bar{Y}7$	15, 14, 13, 12, 11, 10, 9, 7	output $\bar{Y}0$ , $\bar{Y}1$ , $\bar{Y}2$ , $\bar{Y}3$ , $\bar{Y}4$ , $\bar{Y}5$ , $\bar{Y}6$ , $\bar{Y}7$ (active LOW)
GND	8	ground (0 V)
V <sub>CC</sub>	16	positive supply voltage

## 6. Functional description

Table 3. Function table<sup>[1]</sup>

Control			Input			Output							
$\overline{E1}$	$\overline{E2}$	$\overline{E3}$	A2	A1	A0	$\overline{Y7}$	$\overline{Y6}$	$\overline{Y5}$	$\overline{Y4}$	$\overline{Y3}$	$\overline{Y2}$	$\overline{Y1}$	$\overline{Y0}$
H	X	X	X	X	X	H	H	H	H	H	H	H	H
X	H	X											
X	X	L											
L	L	H	L	L	L	H	H	H	H	H	H	H	L
			L	L	H	H	H	H	H	H	H	L	H
			L	H	L	H	H	H	H	H	L	H	H
			L	H	H	H	H	H	H	L	H	H	H
			H	L	L	H	H	H	L	H	H	H	H
			H	L	H	H	H	L	H	H	H	H	H
			H	H	L	H	L	H	H	H	H	H	H
			H	H	H	L	H	H	H	H	H	H	H

[1] H = HIGH voltage level;

L = LOW voltage level;

X = don't care.

## 7. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{CC}$	supply voltage		-0.5	+7	V
$I_{IK}$	input clamping current	$V_I < -0.5$ V or $V_I > V_{CC} + 0.5$ V	-	$\pm 20$	mA
$I_{OK}$	output clamping current	$V_O < -0.5$ V or $V_O > V_{CC} + 0.5$ V	-	$\pm 20$	mA
$I_O$	output current	$V_O = -0.5$ V to $(V_{CC} + 0.5$ V)	-	$\pm 25$	mA
$I_{CC}$	quiescent supply current		-	50	mA
$I_{GND}$	ground current		-	-50	mA
$T_{stg}$	storage temperature		-65	+150	°C
$P_{tot}$	total power dissipation				
	DIP16 package	<sup>[1]</sup>	-	750	mW
	SO16 package	<sup>[2]</sup>	-	500	mW
	SSOP16 package	<sup>[3]</sup>	-	500	mW
	TSSOP16 package	<sup>[3]</sup>	-	500	mW
	DHVQFN16 package	<sup>[4]</sup>	-	500	mW

[1] For DIP16 package:  $P_{tot}$  derates linearly with 12 mW/K above 70 °C.

[2] For SO16 package:  $P_{tot}$  derates linearly with 8 mW/K above 70 °C.

[3] For SSOP16 and TSSOP16 packages:  $P_{tot}$  derates linearly with 5.5 mW/K above 60 °C.

[4] For DHVQFN16 packages:  $P_{tot}$  derates linearly with 4.5 mW/K above 60 °C.

## 8. Recommended operating conditions

**Table 5. Recommended operating conditions**

Voltages are referenced to GND (ground = 0 V)

Symbol	Parameter	Conditions	74HC138			74HCT138			Unit
			Min	Typ	Max	Min	Typ	Max	
V <sub>CC</sub>	supply voltage		2.0	5.0	6.0	4.5	5.0	5.5	V
V <sub>I</sub>	input voltage		0	-	V <sub>CC</sub>	0	-	V <sub>CC</sub>	V
V <sub>O</sub>	output voltage		0	-	V <sub>CC</sub>	0	-	V <sub>CC</sub>	V
T <sub>amb</sub>	ambient temperature		-40	+25	+125	-40	+25	+125	°C
Δt/ΔV	input transition rise and fall rate	V <sub>CC</sub> = 2.0 V	-	-	625	-	-	-	ns/V
		V <sub>CC</sub> = 4.5 V	-	1.67	139	-	1.67	139	ns/V
		V <sub>CC</sub> = 6.0 V	-	-	83	-	-	-	ns/V

## 9. Static characteristics

**Table 6. Static characteristics**

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	T <sub>amb</sub> = 25 °C			T <sub>amb</sub> = -40 °C to +85 °C		T <sub>amb</sub> = -40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
<b>74HC138</b>										
V <sub>IH</sub>	HIGH-level input voltage	V <sub>CC</sub> = 2.0 V	1.5	1.2	-	1.5	-	1.5	-	V
		V <sub>CC</sub> = 4.5 V	3.15	2.4	-	3.15	-	3.15	-	V
		V <sub>CC</sub> = 6.0 V	4.2	3.2	-	4.2	-	4.2	-	V
V <sub>IL</sub>	LOW-level input voltage	V <sub>CC</sub> = 2.0 V	-	0.8	0.5	-	0.5	-	0.5	V
		V <sub>CC</sub> = 4.5 V	-	2.1	1.35	-	1.35	-	1.35	V
		V <sub>CC</sub> = 6.0 V	-	2.8	1.8	-	1.8	-	1.8	V
V <sub>OH</sub>	HIGH-level output voltage	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub>								
		I <sub>O</sub> = -20 μA; V <sub>CC</sub> = 2.0 V	1.9	2.0	-	1.9	-	1.9	-	V
		I <sub>O</sub> = -20 μA; V <sub>CC</sub> = 4.5 V	4.4	4.5	-	4.4	-	4.4	-	V
		I <sub>O</sub> = -20 μA; V <sub>CC</sub> = 6.0 V	5.9	6.0	-	5.9	-	5.9	-	V
		I <sub>O</sub> = -4.0 mA; V <sub>CC</sub> = 4.5 V	3.98	4.32	-	3.84	-	3.7	-	V
		I <sub>O</sub> = -5.2 mA; V <sub>CC</sub> = 6.0 V	5.48	5.81	-	5.34	-	5.2	-	V
V <sub>OL</sub>	LOW-level output voltage	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub>								
		I <sub>O</sub> = 20 μA; V <sub>CC</sub> = 2.0 V	-	0	0.1	-	0.1	-	0.1	V
		I <sub>O</sub> = 20 μA; V <sub>CC</sub> = 4.5 V	-	0	0.1	-	0.1	-	0.1	V
		I <sub>O</sub> = 20 μA; V <sub>CC</sub> = 6.0 V	-	0	0.1	-	0.1	-	0.1	V
		I <sub>O</sub> = 4.0 mA; V <sub>CC</sub> = 4.5 V	-	0.15	0.26	-	0.33	-	0.4	V
		I <sub>O</sub> = 5.2 mA; V <sub>CC</sub> = 6.0 V	-	0.16	0.26	-	0.33	-	0.4	V
I <sub>I</sub>	input leakage current	V <sub>I</sub> = V <sub>CC</sub> or GND; V <sub>CC</sub> = 6.0 V	-	-	±0.1	-	±1.0	-	±1.0	μA
I <sub>CC</sub>	supply current	V <sub>I</sub> = V <sub>CC</sub> or GND; I <sub>O</sub> = 0 A; V <sub>CC</sub> = 6.0 V	-	-	8.0	-	80	-	160	μA

**Table 6. Static characteristics ...continued**

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	T <sub>amb</sub> = 25 °C			T <sub>amb</sub> = -40 °C to +85 °C		T <sub>amb</sub> = -40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
C <sub>I</sub>	input capacitance		-	3.5	-					pF
<b>74HCT138</b>										
V <sub>IH</sub>	HIGH-level input voltage	V <sub>CC</sub> = 4.5 V to 5.5 V	2.0	1.6	-	2.0	-	2.0	-	V
V <sub>IL</sub>	LOW-level input voltage	V <sub>CC</sub> = 4.5 V to 5.5 V	-	1.2	0.8	-	0.8	-	0.8	V
V <sub>OH</sub>	HIGH-level output voltage	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> ; V <sub>CC</sub> = 4.5 V								
		I <sub>O</sub> = -20 µA	4.4	4.5	-	4.4	-	4.4	-	V
		I <sub>O</sub> = -4 mA	3.98	4.32	-	3.84	-	3.7	-	V
V <sub>OL</sub>	LOW-level output voltage	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> ; V <sub>CC</sub> = 4.5 V								
		I <sub>O</sub> = 20 µA	-	0	0.1	-	0.1	-	0.1	V
		I <sub>O</sub> = 4.0 mA	-	0.15	0.26	-	0.33	-	0.4	V
I <sub>I</sub>	input leakage current	V <sub>I</sub> = V <sub>CC</sub> or GND; V <sub>CC</sub> = 5.5 V	-	-	±0.1	-	±1.0	-	±1.0	µA
I <sub>CC</sub>	supply current	V <sub>I</sub> = V <sub>CC</sub> or GND; I <sub>O</sub> = 0 A; V <sub>CC</sub> = 5.5 V	-	-	8.0	-	80	-	160	µA
ΔI <sub>CC</sub>	additional supply current	V <sub>I</sub> = V <sub>CC</sub> - 2.1 V; other inputs at V <sub>CC</sub> or GND; V <sub>CC</sub> = 4.5 V to 5.5 V; I <sub>O</sub> = 0 A								
		per input pin; An inputs	-	150	540	-	675	-	735	µA
		per input pin; $\bar{E}_n$ inputs	-	125	450	-	562.5	-	612.5	µA
		per input pin; E3 input	-	100	360	-	450	-	490	µA
C <sub>I</sub>	input capacitance		-	3.5	-					pF

## 10. Dynamic characteristics

**Table 7. Dynamic characteristics**

Voltages are referenced to GND (ground = 0 V);  $C_L = 50 \text{ pF}$  unless otherwise specified; for test circuit see [Figure 8](#).

Symbol	Parameter	Conditions	$T_{amb} = 25^\circ\text{C}$			$T_{amb} = -40^\circ\text{C}$ to $+85^\circ\text{C}$		$T_{amb} = -40^\circ\text{C}$ to $+125^\circ\text{C}$		Unit
			Min	Typ	Max	Min	Max	Min	Max	
<b>74HC138</b>										
$t_{pd}$	propagation delay	An to $\bar{Y}_n$ ; see <a href="#">Figure 6</a> [1]								
		$V_{CC} = 2.0 \text{ V}$	-	41	150	-	190	-	225	ns
		$V_{CC} = 4.5 \text{ V}$	-	15	30	-	38	-	45	ns
		$V_{CC} = 5 \text{ V}; C_L = 15 \text{ pF}$	-	12	-	-	-	-	-	ns
		$V_{CC} = 6.0 \text{ V}$	-	12	26	-	33	-	38	ns
		E3 to $\bar{Y}_n$ ; see <a href="#">Figure 6</a> [1]								
		$V_{CC} = 2.0 \text{ V}$	-	47	150	-	190	-	225	ns
		$V_{CC} = 4.5 \text{ V}$	-	17	20	-	38	-	45	ns
		$V_{CC} = 5 \text{ V}; C_L = 15 \text{ pF}$	-	14	-	-	-	-	-	ns
		$V_{CC} = 6.0 \text{ V}$	-	14	26	-	33	-	38	ns
		$\bar{E}_n$ to $\bar{Y}_n$ ; see <a href="#">Figure 7</a> [1]								
		$V_{CC} = 2.0 \text{ V}$	-	47	150	-	190	-	225	ns
		$V_{CC} = 4.5 \text{ V}$	-	17	20	-	38	-	45	ns
		$V_{CC} = 5 \text{ V}; C_L = 15 \text{ pF}$	-	14	-	-	-	-	-	ns
		$V_{CC} = 6.0 \text{ V}$	-	14	26	-	33	-	38	ns
$t_t$	transition time	$\bar{Y}_n$ ; see <a href="#">Figure 6</a> and <a href="#">Figure 7</a> [2]								
		$V_{CC} = 2.0 \text{ V}$	-	19	75	-	95	-	110	ns
		$V_{CC} = 4.5 \text{ V}$	-	7	15	-	19	-	22	ns
		$V_{CC} = 6.0 \text{ V}$	-	6	13	-	16	-	19	ns
$C_{PD}$	power dissipation capacitance	$C_L = 50 \text{ pF}; f = 1 \text{ MHz}; V_I = \text{GND to } V_{CC}$ [3]	-	67	-	-	-	-	-	pF

**Table 7. Dynamic characteristics ...continued**Voltages are referenced to GND (ground = 0 V);  $C_L = 50 \text{ pF}$  unless otherwise specified; for test circuit see [Figure 8](#).

Symbol	Parameter	Conditions	$T_{amb} = 25 \text{ }^{\circ}\text{C}$			$T_{amb} = -40 \text{ }^{\circ}\text{C}$ to $+85 \text{ }^{\circ}\text{C}$		$T_{amb} = -40 \text{ }^{\circ}\text{C}$ to $+125 \text{ }^{\circ}\text{C}$		Unit
			Min	Typ	Max	Min	Max	Min	Max	
<b>74HCT138</b>										
$t_{pd}$	propagation delay	An to $\bar{Y}_n$ ; see <a href="#">Figure 6</a> [1]								
		$V_{CC} = 4.5 \text{ V}$	-	20	35	-	44	-	53	ns
		$V_{CC} = 5 \text{ V}; C_L = 15 \text{ pF}$	-	17	-	-	-	-	-	ns
		E3 to $\bar{Y}_n$ ; see <a href="#">Figure 6</a> [1]								
		$V_{CC} = 4.5 \text{ V}$	-	18	40	-	50	-	60	ns
		$V_{CC} = 5 \text{ V}; C_L = 15 \text{ pF}$	-	19	-	-	-	-	-	ns
		$\bar{E}_n$ to $\bar{Y}_n$ ; see <a href="#">Figure 7</a> [1]								
		$V_{CC} = 4.5 \text{ V}$	-	19	40	-	50	-	60	ns
		$V_{CC} = 5 \text{ V}; C_L = 15 \text{ pF}$	-	19	-	-	-	-	-	ns
$t_t$	transition time	$\bar{Y}_n$ ; see <a href="#">Figure 6</a> and <a href="#">Figure 7</a> [2]								
		$V_{CC} = 4.5 \text{ V}$	-	7	15	-	19	-	22	ns
$C_{PD}$	power dissipation capacitance	$C_L = 50 \text{ pF}; f = 1 \text{ MHz}; V_I = \text{GND to } V_{CC} - 1.5 \text{ V}$ [3]	-	67	-	-	-	-	-	pF

[1]  $t_{pd}$  is the same as  $t_{PLH}$  and  $t_{PHL}$ .[2]  $t_t$  is the same as  $t_{THL}$  and  $t_{TLH}$ .[3]  $C_{PD}$  is used to determine the dynamic power dissipation ( $P_D$  in  $\mu\text{W}$ ).

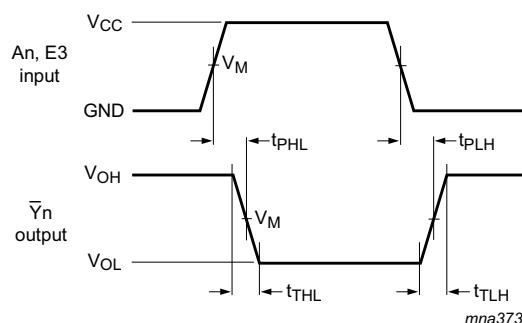
$$P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \sum(C_L \times V_{CC}^2 \times f_o) \text{ where:}$$

 $f_i$  = input frequency in MHz; $f_o$  = output frequency in MHz; $C_L$  = output load capacitance in pF; $V_{CC}$  = supply voltage in V;

N = number of inputs switching;

 $\sum(C_L \times V_{CC}^2 \times f_o)$  = sum of outputs.

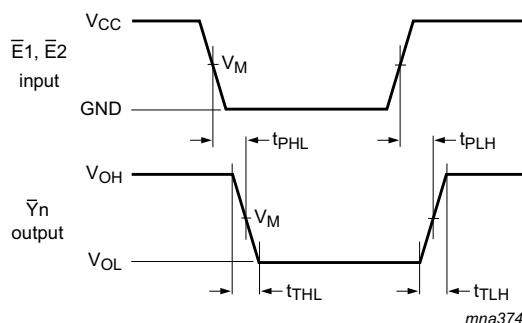
## 11. Waveforms



Measurement points are given in [Table 8](#).

$V_{OL}$  and  $V_{OH}$  are typical voltage output levels that occur with the output load.

**Fig 6.** Propagation delay input ( $A_n$ ) and enable input ( $E_3$ ) to output ( $\bar{Y}_n$ ) and transition time output ( $\bar{Y}_n$ )



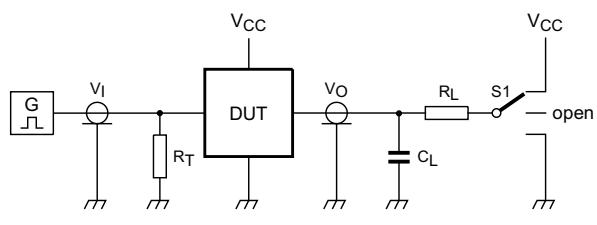
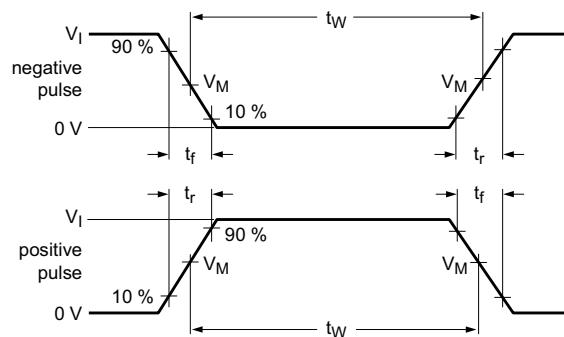
Measurement points are given in [Table 8](#).

$V_{OL}$  and  $V_{OH}$  are typical voltage output levels that occur with the output load.

Fig 7. Propagation delay enable input ( $\bar{E}_n$ ) to output ( $\bar{Y}_n$ ) and transition time output ( $\bar{Y}_n$ )

**Table 8. Measurement points**

Type	Input	Output
	$V_M$	$V_M$
74HC138	0.5V <sub>CC</sub>	0.5V <sub>CC</sub>
74HCT138	1.3 V	1.3 V



Test data is given in [Table 9](#).

Definitions test circuit:

$R_T$  = Termination resistance should be equal to output impedance  $Z_o$  of the pulse generator.

$C_L$  = Load capacitance including jig and probe capacitance.

$R_L$  = Load resistance.

$S1$  = Test selection switch.

**Fig 8. Test circuit for measuring switching times**

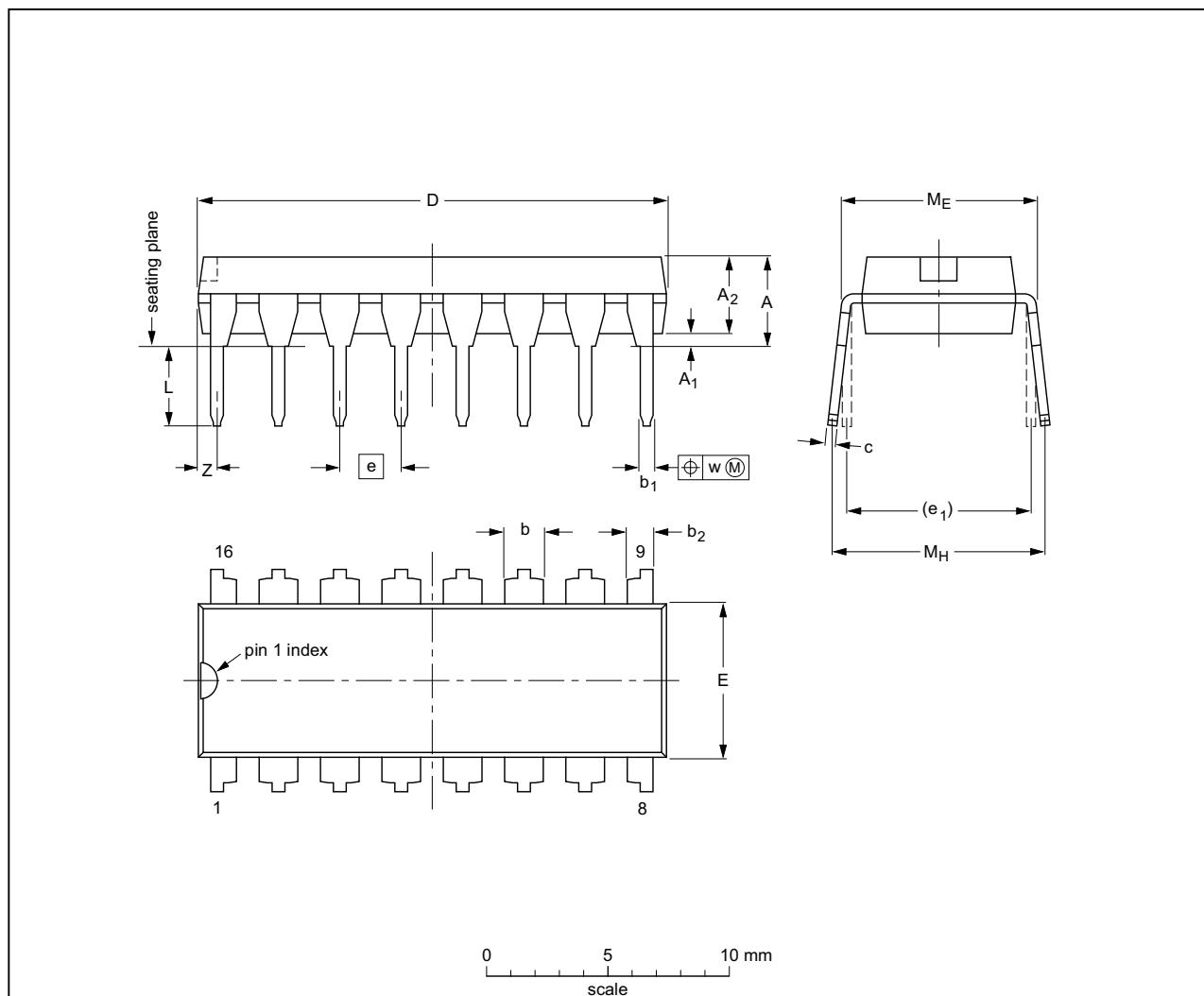
**Table 9. Test data**

Type	Input		Load		S1 position		
	$V_I$	$t_r, t_f$	$C_L$	$R_L$	$t_{PHL}, t_{PLH}$	$t_{PZH}, t_{PHZ}$	$t_{PZL}, t_{PLZ}$
74HC138	$V_{CC}$	6 ns	15 pF, 50 pF	1 k $\Omega$	open	GND	$V_{CC}$
74HCT138	3 V	6 ns	15 pF, 50 pF	1 k $\Omega$	open	GND	$V_{CC}$

## 12. Package outline

DIP16: plastic dual in-line package; 16 leads (300 mil)

SOT38-4



### DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A <sub>1</sub> min.	A <sub>2</sub> max.	b	b <sub>1</sub>	b <sub>2</sub>	c	D <sup>(1)</sup>	E <sup>(1)</sup>	e	e <sub>1</sub>	L	M <sub>E</sub>	M <sub>H</sub>	w	Z <sup>(1)</sup> max.
mm	4.2	0.51	3.2	1.73 1.30	0.53 0.38	1.25 0.85	0.36 0.23	19.50 18.55	6.48 6.20	2.54	7.62	3.60 3.05	8.25 7.80	10.0 8.3	0.254	0.76
inches	0.17	0.02	0.13	0.068 0.051	0.021 0.015	0.049 0.033	0.014 0.009	0.77 0.73	0.26 0.24	0.1	0.3	0.14 0.12	0.32 0.31	0.39 0.33	0.01	0.03

### Note

1. Plastic or metal protrusions of 0.25 mm (0.01 inch) maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT38-4						95-01-14 03-02-13

Fig 9. Package outline SOT38-4 (DIP16)

SO16: plastic small outline package; 16 leads; body width 3.9 mm

SOT109-1

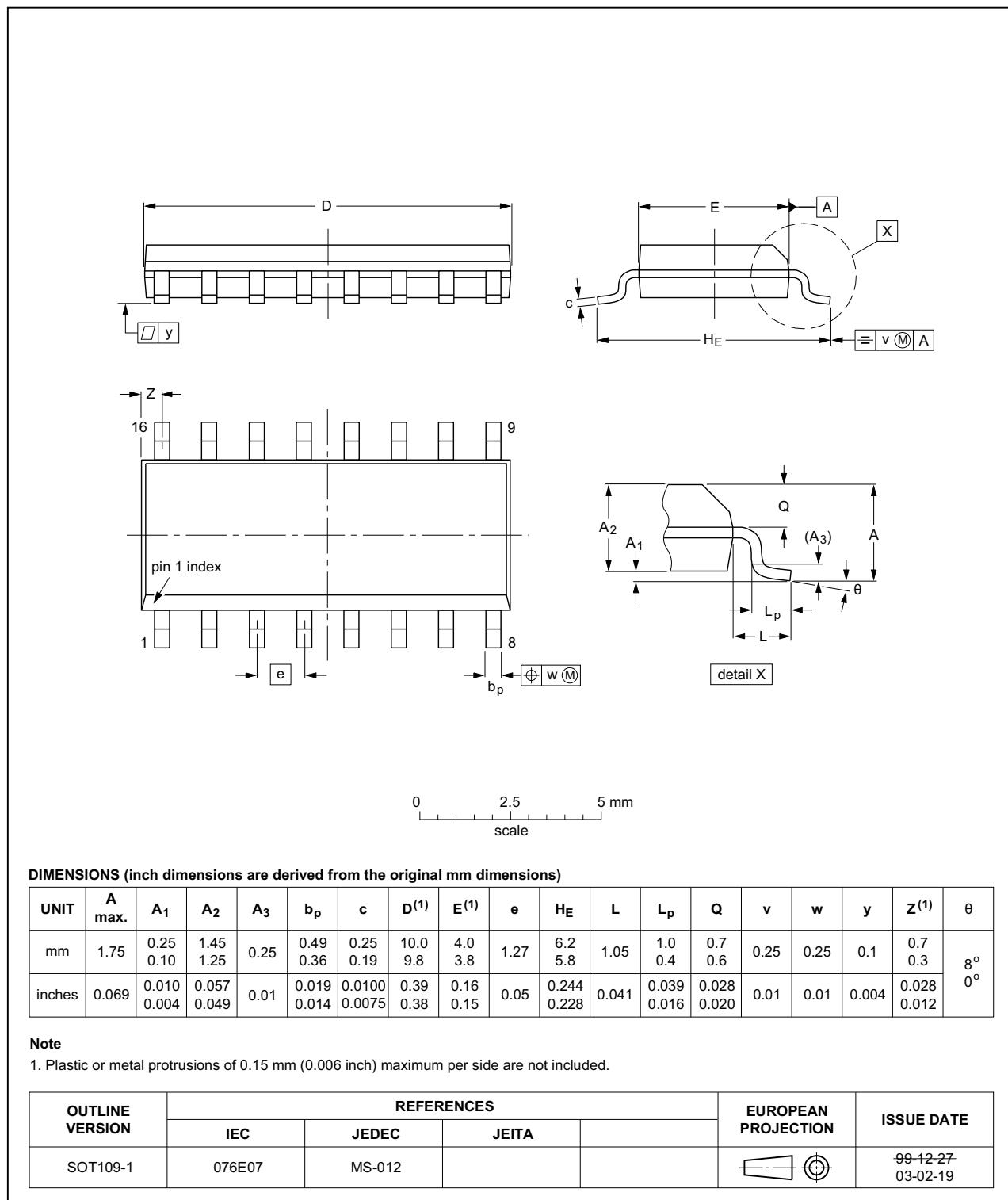


Fig 10. Package outline SOT109-1 (SO16)

TSSOP16: plastic thin shrink small outline package; 16 leads; body width 4.4 mm

SOT403-1

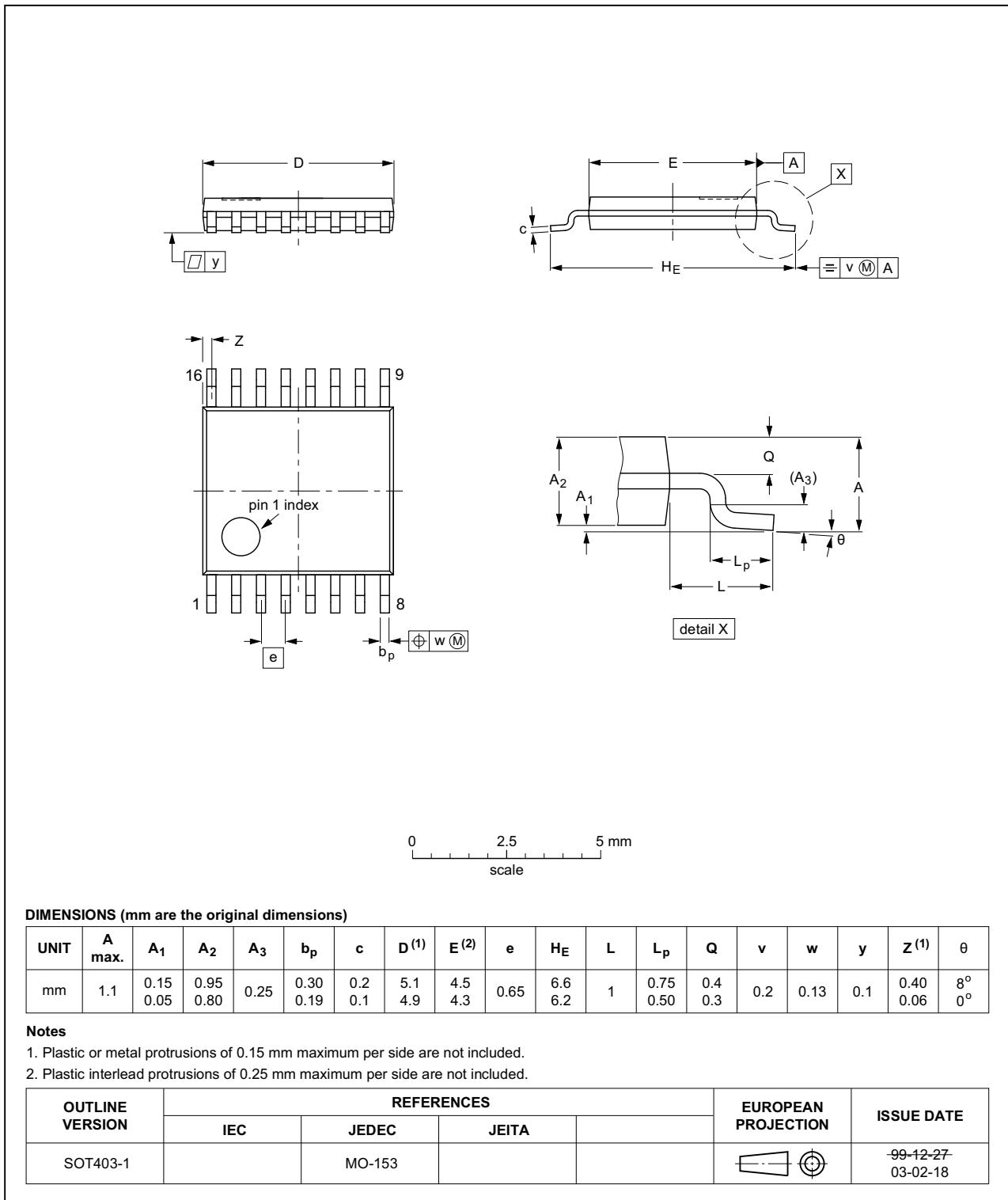


Fig 11. Package outline SOT403-1 (TSSOP16)

SSOP16: plastic shrink small outline package; 16 leads; body width 5.3 mm

SOT338-1

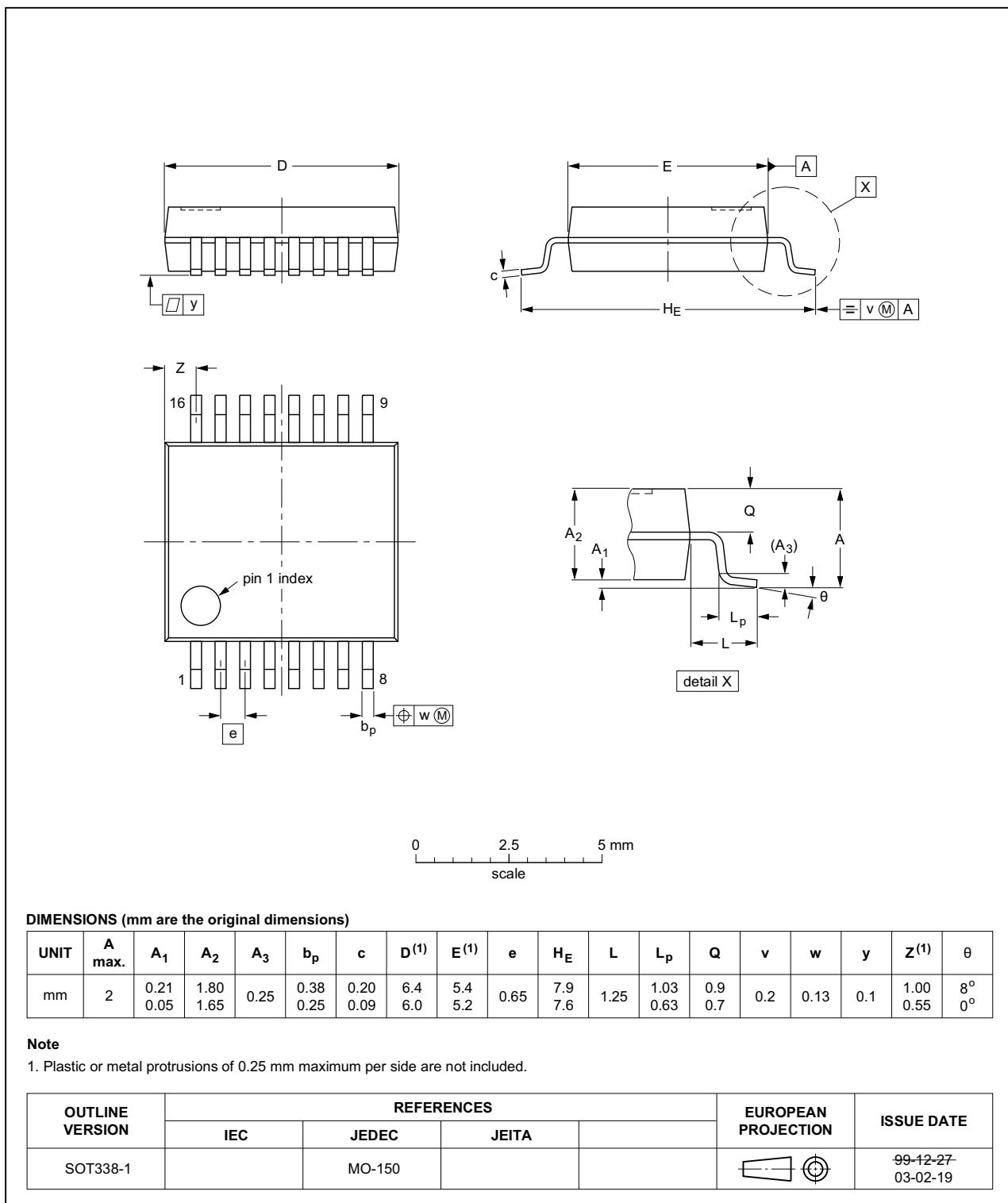
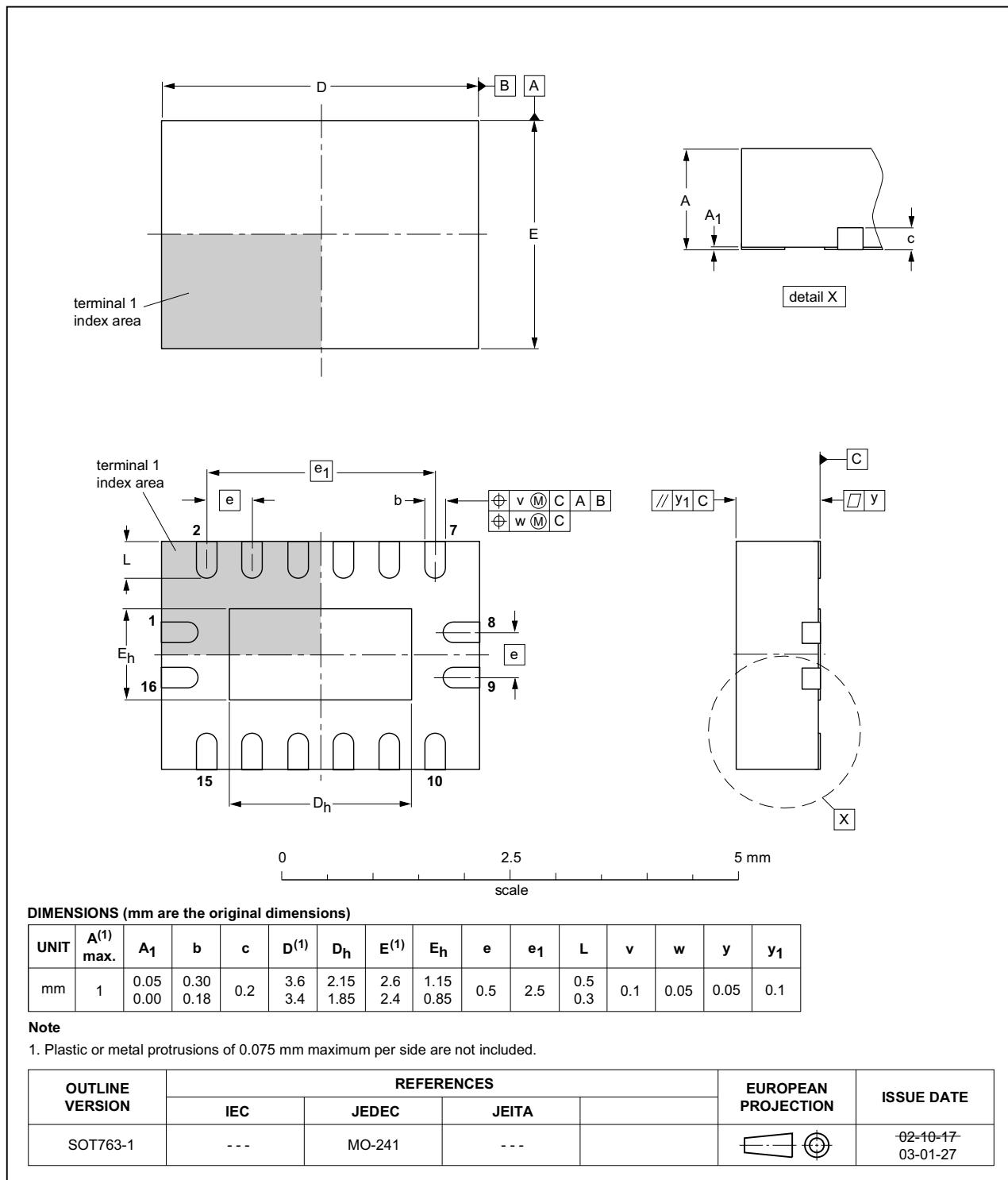


Fig 12. Package outline SOT338-1 (SSOP16)

**DHVQFN16: plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads; 16 terminals; body 2.5 x 3.5 x 0.85 mm** SOT763-1



**Fig 13. Package outline SOT763-1 (DHVQFN16)**

## 13. Abbreviations

**Table 10. Abbreviations**

Acronym	Description
CMOS	Complementary Metal Oxide Semiconductor
DUT	Device Under Test
ESD	ElectroStatic Discharge
HBM	Human Body Model
TTL	Transistor-Transistor Logic
MM	Machine Model

## 14. Revision history

**Table 11. Revision history**

Document ID	Release date	Data sheet status	Change notice	Supersedes
74HC_HCT138 v.5	20150126	Product data sheet	-	74HC_HCT138 v.4
Modifications:			<ul style="list-style-type: none"> <li>• <a href="#">Table 6</a>: OFF-state output current removed because device has no 3-state outputs.</li> <li>• <a href="#">Table 7</a>: Power dissipation capacitance condition for 74HCT138 is corrected.</li> </ul>	
74HC_HCT138 v.4	20120627	Product data sheet	-	74HC_HCT138 v.3
Modifications:			<ul style="list-style-type: none"> <li>• The format of this data sheet has been redesigned to comply with the new identity guidelines of NXP Semiconductors.</li> <li>• Legal texts have been adapted to the new company name where appropriate.</li> <li>• SOT38-1 changed to SOT38-4.</li> </ul>	
74HC_HCT138 v.3	20051223	Product data sheet	-	74HC_HCT138_CNV v.2
Modifications:			<ul style="list-style-type: none"> <li>• The format of this data sheet has been redesigned to comply with the new presentation and information standard of Philips Semiconductors.</li> <li>• <a href="#">Section 3 “Ordering information”</a>, <a href="#">Section 5 “Pinning information”</a> and <a href="#">Section 12 “Package outline”</a>: Added DHVQFN package information</li> <li>• <a href="#">Section 9 “Static characteristics”</a>: Added from the family specification</li> </ul>	
74HC_HCT138_CNV v.2	19970827	Product specification	-	-

## 15. Legal information

### 15.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nxp.com>.

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